

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
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STEPHAN HEINRICH	10/26/2021
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Property Type	Number
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DATE SIGNED:	11/24/2021
Total Attachments: 2	
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ASSIGNMENT AND DECLARATION (37 C.F.R. 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 C.F.R. 1.76)

Title of Invention

**METHOD FOR DEPOSITING AN EPITAXIAL LAYER ON A FRONT SIDE OF A
SEMICONDUCTOR WAFER, AND DEVICE FOR CARRYING OUT THE METHOD**

As a below named inventor, I hereby declare that:

This declaration is directed to:



The attached application, or



United States application or PCT international application number
PCT/EP2020/061882 filed on April 29, 2020. (I hereby authorize the
insertion of the application filing date and number when they become known.)

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I am aware of the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in 37 C.F.R. § 1.56.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I do hereby assign, sell and set over to Siltronic AG, a corporation organized and existing under the laws of the state or country of Germany, and having a place of business at Einsteinstr. 172, 81677 Munich, Germany, hereinafter referred to as the ASSIGNEE, its successors, assigns or other legal representatives, my entire right, title and interest, domestic and foreign, in and to the inventions and discoveries in the above-identified application including the right of said ASSIGNEE, its successors, assigns or other legal representatives to make applications and to receive Letters Patent for said inventions and discoveries in any and all foreign countries in its or their own name or names, or in my name, at its or their election, and I hereby assign, sell and set over to said ASSIGNEE, its successors, assigns or other legal representatives, all rights of priority, including any provisional applications, in and to said inventions and discoveries in all countries, including all applications claiming benefit of the filing date hereof, continuations, continuations-in-part, divisionals, reexaminations and reissue applications.

And I hereby agree for myself, my heirs, successors, assigns or other legal representatives to execute any and all papers, including applications for Letters Patent of any and all kinds and in any and all countries and to perform any and all acts which said ASSIGNEE, its successors, assigns or other legal representatives may deem necessary to secure thereto the rights herein assigned, sold and set over.

And I hereby represent and warrant that I have not granted any rights inconsistent with the rights granted herein.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years or both.

LEGAL NAME OF INVENTOR

Inventor: Joerg HABERECHT

Date: 26.10.2021

Signature: Joerg Haberecht

Page 1 of 2 (Supplemental Sheet with Additional Joint Inventors is attached if necessary)

Note: An Application Data Sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form.

Attorney Docket Number

WSAGN0170PUSA
2019P00061 WOUSSUPPLEMENTAL SHEET FOR ASSIGNMENT AND DECLARATION
(37 C.F.R. 1.63) FOR UTILITY OR DESIGN APPLICATION USING
AN APPLICATION DATA SHEET (37 C.F.R. 1.76)Additional Inventors
Page 3

Title of Invention

METHOD FOR DEPOSITING AN EPITAXIAL LAYER ON A FRONT SIDE OF A
SEMICONDUCTOR WAFER, AND DEVICE FOR CARRYING OUT THE METHOD

Legal Name of Additional Joint Inventor:

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Date:

26.10.21Signature: S. Heinrich

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26.10.21Signature: R. Schäfer

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Date:

26.10.21Signature: R. Stein